

MA24F70

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Super high speed switching characteristic: $t_{tr} = 15 \text{ ns}$ (typ.)
- Low impedance by clip bonding package (TMP)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	700	V
Non-repetitive peak reverse surge voltage	V_{RSM}	700	V
Forward current *1	I_F	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	20	A
Junction temperature	T_j	-40 to +150	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +150	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Package

- Code
TMiniP2-F1
- Pin Name
1: Anode
2: Cathode

■ Marking Symbol: H1

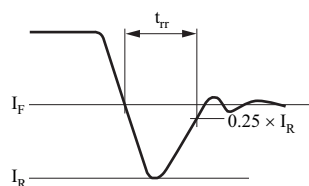
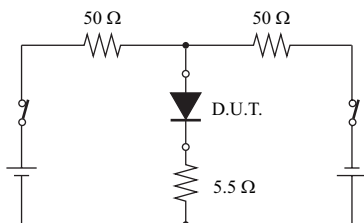
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

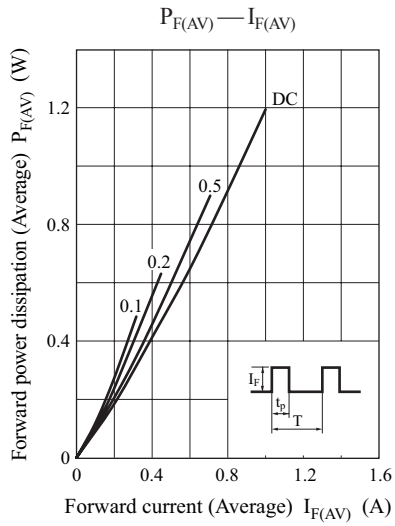
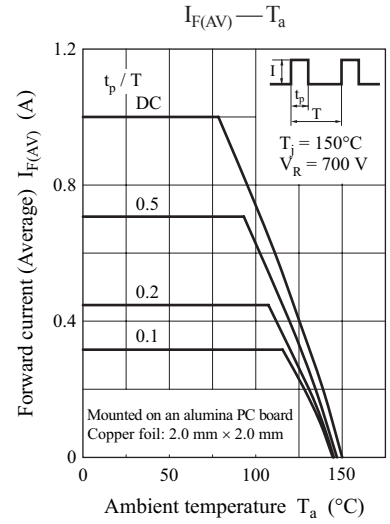
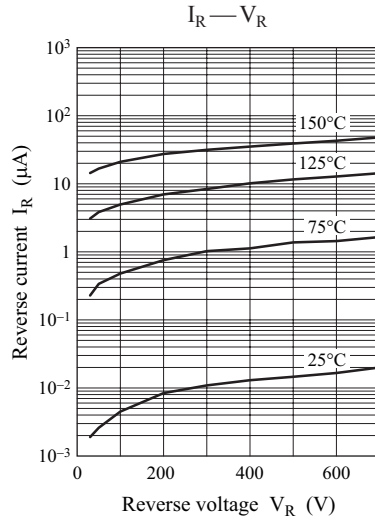
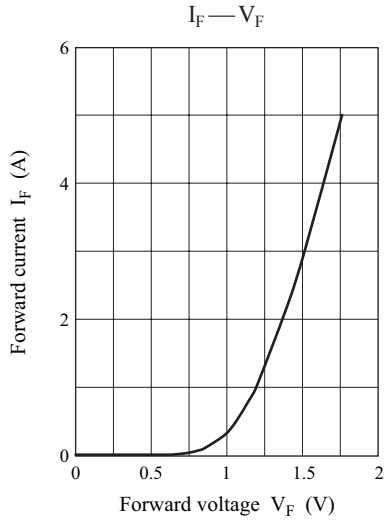
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 1.0 \text{ A}$		1.3	1.7	V
Reverse current	I_{RRM}	$V_{RRM} = 700 \text{ V}$			20	μA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		25		pF
Reverse recovery time *	t_{tr}	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}$ $I_{tr} = 0.25 \text{ A}$		15	45	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

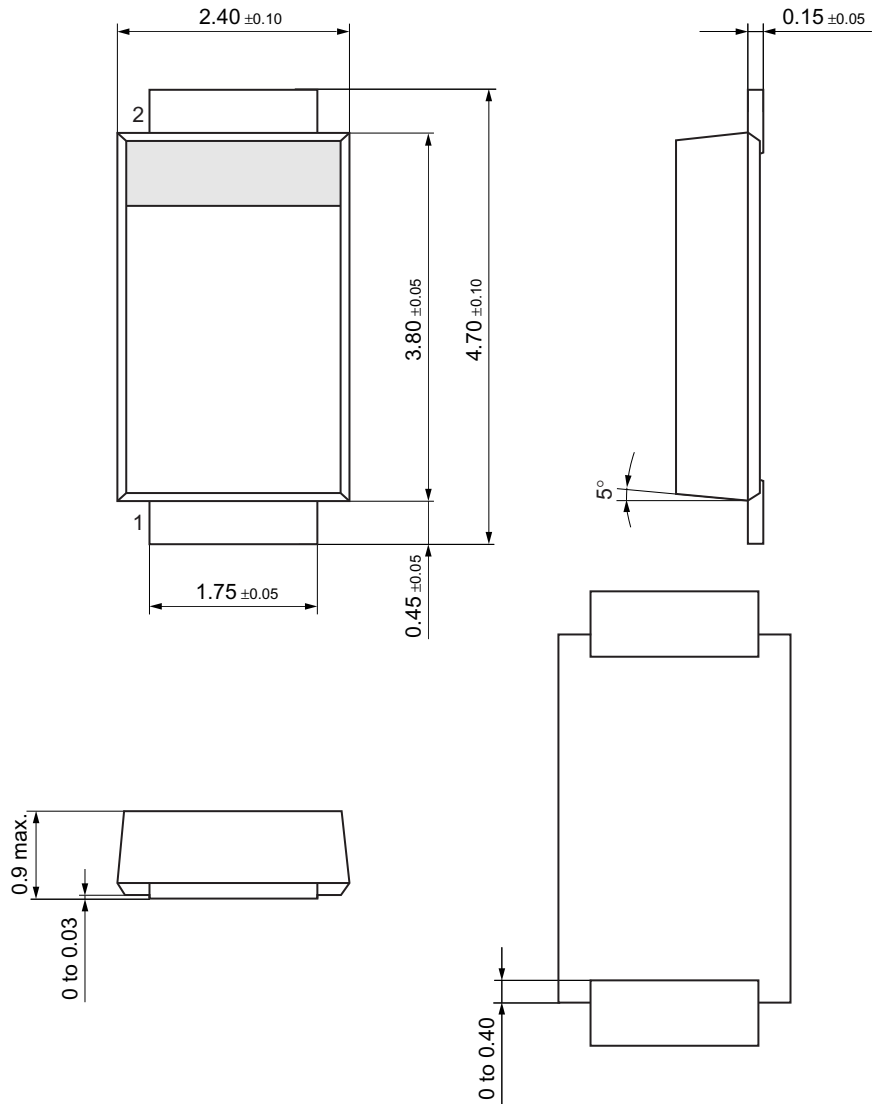
3. *: t_{tr} measurement circuit





TMiniP2-F1

Unit: mm



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